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(54) FORMING METHOD FOR BUMP ELECTRODE

(57) Abstract:

PURPOSE: To equalize the height and size of a bump electrode by attracting the upper surface of a substrate by an attracting jig combining the electrode and plating the lower surface of the substrate under the state in which the lower surface is separated only by predetermined size from the upper surface of a plating device with no positioning pin.

CONSTITUTION: A semiconductor substrate 13 is attracted, an attracting jig 33 is moved by operating a lever, etc., and the semiconductor substrate 13 is held so that the lower surface of the substrate is separated only by size G from the upper end of a cylindrical body 30. When a plating liquid 35 is blown up from the lower section of the cylindrical body 30 under the state, the plating liquid 35 collides with the lower surface of the semiconductor substrate 13 and is guided and flows and spreads in the radial direction, and passes through a clearance between the upper surface of the cylindrical body 30 and the semiconductor substrate 13 and overflows from all directions. Since there is no support pin, positioning pin, etc. at that time, the surface of a liquid does not move vertically due to the disturbance

of the overflowing plating liquid 35, and the plating liquid 35 does not go round up to the side surface and back of the semiconductor substrate 13.

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